March 3, 2017

Product change
EPCOS CeraLink capacitors up to +150 °C operating temperature

The maximum operating temperature of the following EPCOS CeraLink™ multilayer capacitors has been increased from +125 °C (150 °C for max. 5% of the operating time) to +150 °C. The maximum ripple current capability was increased at the same time.

Affected products

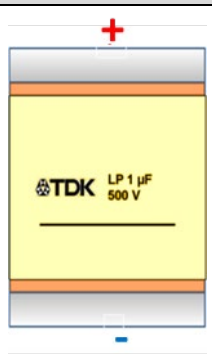
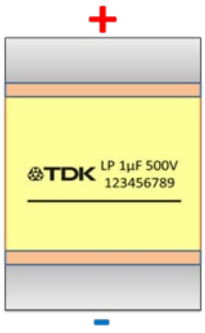
Ordering code (Type)	New specification		Previous specification	
	Max. T_{dev} = 150 °C		Max. T_{dev} = 125 °C	
	I_{op} 100 kHz T_A = 85 °C [A]	I_{op} 100 kHz T_A = 105 °C [A]	I_{op} 100 kHz T_A = 85 °C [A]	I_{op} 100 kHz T_A = 105 °C [A]
B58031I5105M062 (LP, 500 V, L leads)	11.4	9.7	7.5	5.2
B58031U5105M062 (LP, 500 V, J leads)	11.4	9.7	7.5	5.2
B58031I7504M062 (LP, 700 V, L leads)	7.1	6.5	5.4	4.4
B58031U7504M062 (LP, 700 V, J leads)	7.1	6.5	5.4	4.4
B58033I5206M001 (SP, 500 V)	41.3	32.2	31.5	24.5
B58033I7106M001 (SP, 700 V)	32.6	27.2	26	17.7

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Chairman of the Supervisory Board: Dr. Werner Faber
Management Board: Joachim Zichlarz, Chairman · Joachim Thiele · Dr. Norbert Hess
www.epcos.com

March 3, 2017

After the successful production start of the affected CeraLink capacitors, we will skip the marking of every single component with the batch number.

Examples of new and previous marking

New		Previous	
LP L-lead	LP J-lead	LP L-lead	LP J-lead
			
SP		SP	
			

Scheduled date of introduction: July 1, 2017

Except for the changes described above, no further other effects on appearance, function, processability, materials or the production process.

The plant in Deutschlandsberg, Austria, is certified according to ISO/TS 16949 and ISO 9001. Production release will be carried out in conformance with ISO/TS 16949. The established process steps will not be changed. All quality assurance measures will be maintained.

The data sheets may be downloaded from the product catalog under www.epcos.com/ceralink.

Enclosure PCN (ID No. PPD18/T121)

Contact Dr. Stefan Benkhof, PPD PTC PM, Munich

Customers are asked to address inquiries directly to their sales contacts.

Product / Process Change Notification

1. ID No.: PPD18/T121		**2. Date of announcement:** March 3, 2017	
3. Product / product group: EPCOS CeraLink™ capacitors	**Old ordering code:** B58031I5105M062 B58031I7504M062 B58031U5105M062 B58031U7504M062 B58033I5206M001 B58033I7106M001	**New ordering code:** No change	**Customer part number:**

4. Description of change:

Increase of the specified max. operating device temperature for all CeraLink capacitors from OLD: +125 °C (150 °C for max. 5% of the operating time) to NEW: +150 °C

Increase of max. ripple current capability of all CeraLink capacitors.

After succesful product start, we will skip the marking of every single component with the batch number.

5. Effect on the product or for the customer (benefit, quality, specification, lead time):

Except for the changes described above, no other effects on appearance, function, processability, materials or the production process.

6. Quality assurance measures / risk assessment:

The plant in Deutschlandsberg, Austria, is certified according to ISO/TS 16949 and ISO 9001. Production release will be carried out in conformance with ISO/TS 16949. The established process steps will consequently not be changed. All quality assurance measures will be maintained.

7. Scheduled date of change: July 1, 2017

8. Estimated date of first delivery of changed product: July 1, 2017

If EPCOS does not receive notification to the contrary within a period of 10 weeks, EPCOS assumes that the customer agrees to the change. For an interim period we cannot rule out that old as well as new products will be shipped.

Quality Management Name Markus Weiglhofer	Signature signed Weiglhofer
Product Marketing Name Dr. Stefan Benkhof Tel. +49 89 54020 2970 Email stefan.benkhof@epcos.com	Signature signed Stefan Benkhof

Customer feedback

Customer acknowledgement — Signature